Docket No.: 1016-012

the specification of which is attached hereto

## **DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I hereby declare that:

My residence, post office address, and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought on the invention entitled:

## VIA-SEA LAYOUT IN INTEGRATED CIRCUITS

	_ as Application S		. 6 .1	1
-		ed and understand the conte as amended by any amendmer		
America before the the same was not in prior to this applied	is invention therectin public use or or cation. I acknowle	the same was ever known or of or more than one year prior as ale in the United States of the edge the duty to disclose informaccordance with title 37, Commence with title 37,	r to this app America moormation w	olication, and that ore than one year hich is known to
I hereby claim for		fits under Title 35, United Sta		ection 119(a)-(d)
365(a) of any PCT the United States,	international app listed below and 's certificate havi	plication(s) for patent or inveblication which designated at have also identified belowing a filing date before that	least one co	ountry other than n application for
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I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s), or Section 365(c) of any PCT international application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of Title 35, United States Code, Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

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## **Prior U.S. Application(s):**

Serial No.

Filing Date

Status: Patented, Pending, Abandoned

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby revoke any previous Powers of Attorney and appoint the following attorney(s) and/or agent(s), each said individual being a member or associate of The Law Offices of Mikio Ishimaru or being employed by Chartered Semiconductor Manufacturing Ltd.:

Mikio Ishimaru

Reg. No. 27,449

for so long as they remain with such law offices or company with full power of substitution and revocation, to prosecute this application and to transact in connection therewith all business in the Patent and Trademark Office and before competent International Authorities; said appointment to be to the exclusion of myself and my other attorney(s); and all future correspondence should be addressed to:

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The Law Offices of Mikio Ishimaru
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Sunnyvale, California 94087

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